

FOR IMMEDIATE RELEASE

Celsia Introduces Next Generation Heat Sink Technology, Furthering its Goal of Replacing Heat Pipes in Computer, Telecommunications, and LED Lighting Applications

Heat Sinks Using Second Generation NanoSpreader Vapor Chambers Outperform Heat Pipe Solutions by 30 Percent

SAN JOSE, California, March 18, 2008 – Already credited with making vapor chambers (a once exotic heat sink technology) thin, light and affordable, Celsia Technologies (“Celsia”) today introduces its second generation NanoSpreader. Thermal transfer properties from the heat source to the vapor have been improved by 66 percent over the first generation, using a re-engineered internal structure that leverages the company’s patented combination of copper, liquid and vapor. These changes, developed through extensive collaboration with industry-leading computing and graphics manufacturers, give the new NanoSpreader the ability to trump heat pipes as the king of cost-effective cooling.

“While maintaining reliability standards and manufacturing costs, our engineers have designed this next generation product to offer up to 30 percent better thermal performance than solutions using traditional heat pipes, and their design flexibility allows them to be used in some unexpected ways,” said Joe Formichelli, Celsia’s CEO. “For instance, a single NanoSpreader can be made up to 70mm wide and attach *directly* to the heat source, eliminating the need for additional components while completely covering even a very large hot spot.”

Nanospreaders are patented copper encased two-phase vapor chambers into which pure water is vacuum sealed. The liquid is absorbed by a copper wick and passed as vapor through a micro-perforated copper sheet where it cools and returns as liquid to the wick. The latest generation technology is ideally suited for solving some of today’s biggest thermal challenges: cooling the latest microprocessors, reliably operating in harsh environments, and effectively dissipating heat in small spaces. For examples of specific industry solutions, please visit http://celsiatechnologies.com/industry_solutions.asp.

Computer - Cooling the Latest Microprocessors

Whether it is a CPU used to power an entire computer or a special graphics processor (GPU) used by high end gamers or CAD designers, thermal requirements for cooling microprocessors are more demanding than ever before. Celsia’s new NanoSpreaders can cool power densities up to 150 watts/cm² while offering excellent multi-directional thermal spreading as low as 0.02° Celsius per watt. Additionally, NanoSpreaders can withstand clamping forces up to 90 PSI, giving thermal designers the option of attaching them directly to the CPU/GPU.

Telecommunications Infrastructure - Reliably Operating in Harsh Environments

Equipment that operates as part of the telecommunication backbone (such as repeaters and base stations) must be reliable in some of the harshest weather imaginable. With no moving parts, Celsia NanoSpreaders are designed and tested to withstand repeated exposure of -40° to +100° Celsius.

LED Lighting - Effectively Dissipating Heat in Small Spaces

While LED lighting technology is quickly offering an energy efficient alternative to other lighting technologies, it requires cooling solutions that are effective in small areas. The efficiency of Celsia's NanoSpreaders combined into a remarkably thin package (from 1.5mm) allows lighting designs with higher lumens/watt.

For more information on Celsia or the technical details behind NanoSpreaders please visit Celsiatechnologies.com. A downloadable fact sheet describes the technology, lists 21 standard sizes, and includes information on thermal resistance and reliability testing. For frequently asked questions, visit http://celsiatechnologies.com/engineering_faq.asp.

Pricing and Availability

The second-generation devices are available now, starting at under \$2.00. To obtain application specific pricing, submit the quote request form found at <http://celsiatech.com/quote.asp>.

About Celsia Technologies

Celsia Technologies is a full solution provider and licensor of thermal management products and technology for the PC, consumer electronics, lighting and display industries. The company is a leader in developing and commercializing next-generation cooling solutions built on patented micro thermofluidic technology. Celsia Technologies' extensive intellectual property portfolio includes patents registered in Korea, the U.S., Japan and Taiwan, with patents pending in the EU, Russia, India and China.

Forward Looking Statements

This press release contains forward-looking statements, involving risks and uncertainties. Such statements are based on management's current expectations and are subject to certain factors, risks, and uncertainties that may cause actual results, events and performance to differ materially from those referred to or implied by such statements. In addition, actual future results may differ materially from those anticipated, depending on a variety of factors which include, but are not limited to, Celsia Technologies' ability to attract investors, Celsia Technologies' future operating results, and general economic conditions affecting consumer spending, including uncertainties relating to global political conditions, such as terrorism and the conflict with Iraq. Readers are cautioned not to place undue reliance on these forward-looking statements, which speak only as of the date hereof. Celsia Technologies does not intend to update any of the forward-looking statements after the date of this release to conform these statements to actual results or to changes in its expectations, except as may be required by law.

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